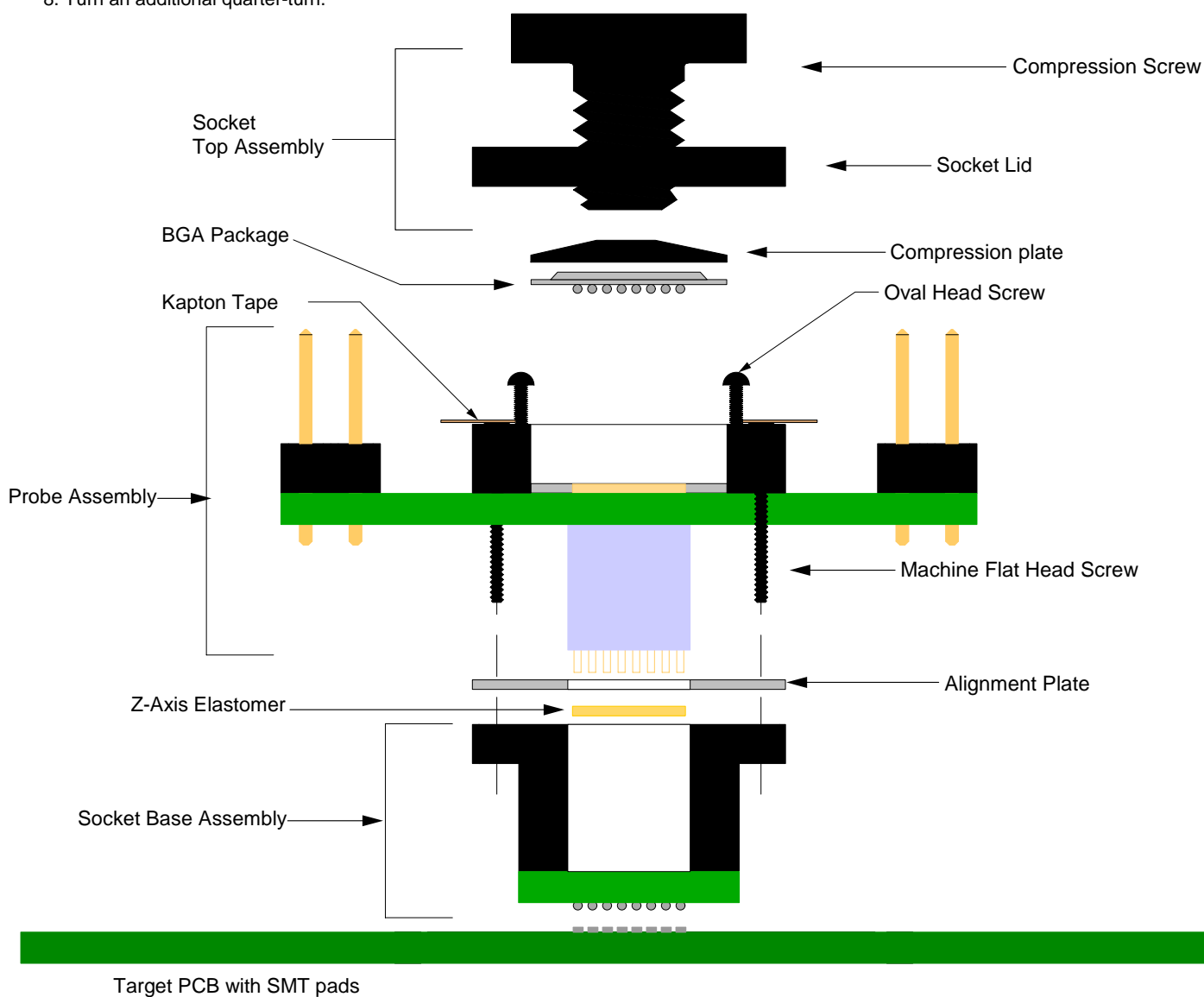


GHz BGA Probe Adapter (surface mount)

Assembly Instructions

1. Reflow Socket Base assembly to the target PCB (as per BGA surface mount foot soldering instructions).
2. Place the square piece of elastomer provided into the socket base (rotation and 'side up' orientation are not critical).
3. Adjust the elastomer to sit into the Socket Base cavity and place the alignment plate on top of the Socket Base.
4. Place probe assembly into the socket, remove kapton tape and assemble with the hardware provided (four 0-80 machine flat head screws).
5. Place BGA package (solder ball side down) into the socket on the probe assembly. NOTE: BGA orientation is critical.
5. Place the compression plate (if required*) on top of the BGA package.
6. Place the socket top assembly through oval head screws on to the socket using the key hole slot and slide.
7. Turn the compression screw clockwise, until it makes contact with the compression plate or the BGA package.
8. Turn an additional quarter-turn.



*Ironwood Electronics technical staff will determine (from your package spec) if a compression or alignment plate is required

